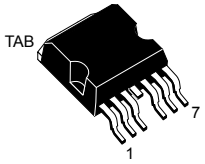
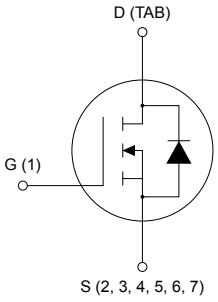
N-channel 100 V, 1.9 mΩ max., 292 A STripFET F8 Power MOSFET in an H²PAK-6 package



H²PAK-6



AM00676v1

Features

Order code	V_{DS}	$R_{DS(on)}$ max.	I_D
STH280N10F8-6	100 V	1.9 mΩ	292 A

- 175 °C maximum operating junction temperature
- 100% avalanche tested
- Excellent FoM (figure of merit)

Applications

- Industrial motor control
- Industrial tools, motor drives and equipment

Description

The STH280N10F8-6 is a 100 V N-channel enhancement mode Power MOSFET designed in STripFET F8 technology featuring an enhanced trench gate structure.

It ensures a state-of-the-art of figure of merit for very low on-state resistance while reducing internal capacitances and gate charge for faster and more efficient switching.

Product status link
STH280N10F8-6

Product summary	
Order code	STH280N10F8-6
Marking(1)	280N10F8
Package	H²PAK-6
Packing	Tape and reel

1. *Engineering samples are clearly identified with a dedicated special symbol in the marking of each unit.*

1 Electrical ratings

Table 1. Absolute maximum ratings (at T_C = 25 °C unless otherwise specified)

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	100	V
V_{GS}	Gate-source voltage	±20	V
I_D[1]	Drain current (continuous) at T_C = 25 °C[2]	292	A
	Drain current (continuous) at T_C = 100 °C[2]	206	
	Drain current (continuous) at T_C = 25 °C[3]	240	
I_{DM}[1][2][4]	Drain current (pulsed), t_P = 10 µs	1170	A
P_{TOT}	Total power dissipation at T_C = 25 °C	341	W
I_{AS}	Single pulse avalanche current (pulse width limited by maximum junction temperature)	90	A
E_{AS}	Single pulse avalanche energy (starting T_J = 25 °C, I_D = 90 A, R_G = 25 Ω)	600	mJ
T_J	Operating junction temperature range	-55 to 175	°C
T_{stg}	Storage temperature range		°C

1. *Specified by design, not tested in production.*
2. *This is the theoretical current value only related to the silicon.*
3. *This current value is limited by package.*
4. *Pulse width is limited by safe operating area.*

Table 2. Thermal data

Symbol	Parameter	Value	Unit
R_{thJA}[1]	Thermal resistance, junction-to-ambient (on 2s2p FR-4 board vertical in still area)	14.8	°C/W
R_{thJC}	Thermal resistance, junction-to-case	0.44	°C/W

1. *Measured on 4 layer PCB according to Jedec 51.2 in natural convection (still air).*

2 Electrical characteristics

T_J = 25 °C unless otherwise specified.

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	V_{GS} = 0 V, I_D = 1 mA	100			V
I_{DSS}	Zero gate voltage drain current	V_{DS} = 100 V, V_{GS} = 0 V			1	µA
		V_{DS} = 100 V, V_{GS} = 0 V, T_J = 125 °C(1)			100	
I_{GSS}	Gate-body leakage current	V_{GS} = 20 V, V_{DS} = 0 V			100	nA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 250 µA	2		4	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 90 A		1.5	1.9	mΩ
R_G	Gate resistance	f = 1 MHz		0.6		Ω

1. *Specified by design and evaluated by characterization, not tested in production.*

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}(1)	Input capacitance	V_{DS} = 50 V, f = 1 MHz, V_{GS} = 0 V	-	11200	-	pF
C_{oss}(1)	Output capacitance		-	2400	-	pF
C_{rss}(1)	Reverse transfer capacitance		-	99	-	pF
Q_g(1)	Total gate charge	V_{DD} = 50 V, I_D = 90 A, V_{GS} = 0 to 10 V	-	177	-	nC
Q_{gs}(1)	Gate-source charge		-	53	-	nC
Q_{gd}(1)	Gate-drain charge		-	44	-	nC
$Q_{g(sync)}$(1)	Total gate charge, sync. MOSFET	V_{DS} = 0.1 V, V_{GS} = 0 to 10 V	-	151	-	nC
Q_{oss}(1)	Output charge	V_{DD} = 50 V, V_{GS} = 0 V	-	212	-	nC

1. *Specified by design and evaluated by characterization, not tested in production.*

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$(1)	Turn-on delay time	V_{DD} = 50 V, I_D = 90 A, R_G = 4.7 Ω, V_{GS} = 10 V	-	40	-	ns
t_r(1)	Rise time		-	40	-	ns
$t_{d(off)}$(1)	Turn-off delay time		-	95	-	ns
t_f(1)	Fall time		-	35	-	ns

1. *Specified by design and evaluated by characterization, not tested in production.*

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD} (1)(2)	Forward on current (continuous)	T_C = 25 °C	-		227	A
V_{SD}	Forward on voltage	I_{SD} = 90 A, V_{GS} = 0 V	-		1.2	V
t_{rr} (2)	Reverse recovery time	I_D = 90 A, di/dt = 100 A/µs, V_{DD} = 80 V	-	87		ns
Q_{rr} (2)	Reverse recovery charge		-	212		nC
I_{RRM} (2)	Reverse recovery current		-	4.9		A

1. *This is the theoretical current value only related to the silicon.*
2. *Specified by design and evaluated by characterization, not tested in production.*

2.1 Electrical characteristics (curves)

Figure 1. Total power dissipation vs temperature

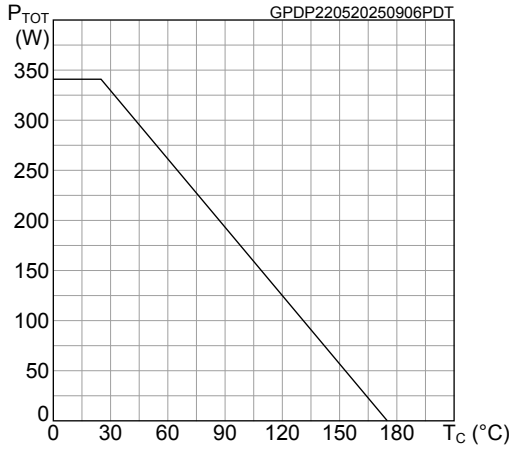


Figure 2. Drain current vs case temperature

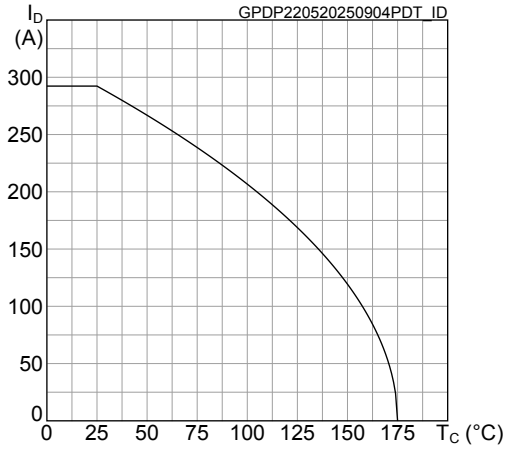


Figure 3. Safe operating area

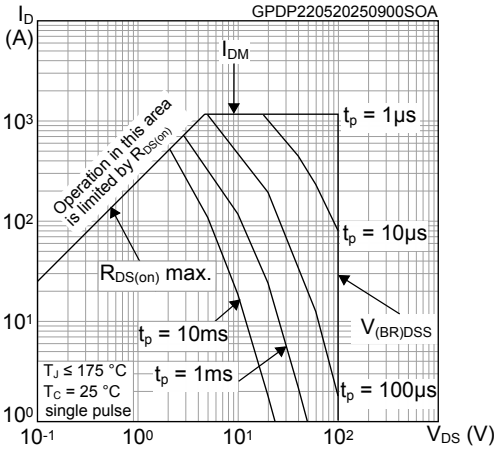


Figure 4. Normalized transient thermal impedance

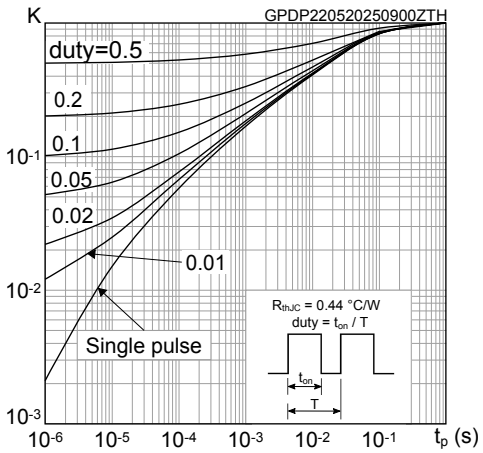


Figure 5. Typical output characteristics

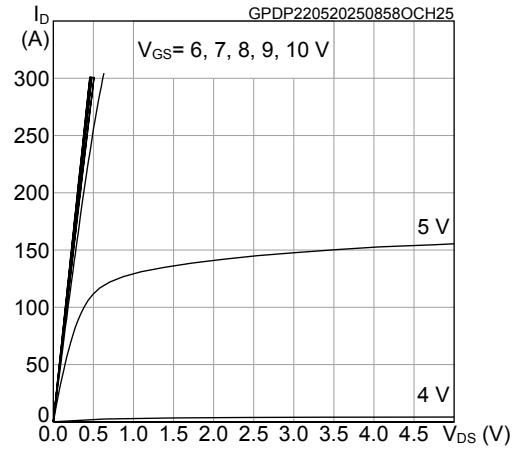


Figure 6. Typical gate charge characteristics

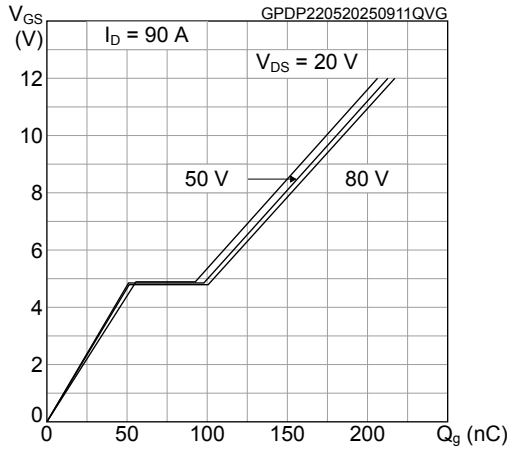


Figure 7. Typical capacitance characteristics

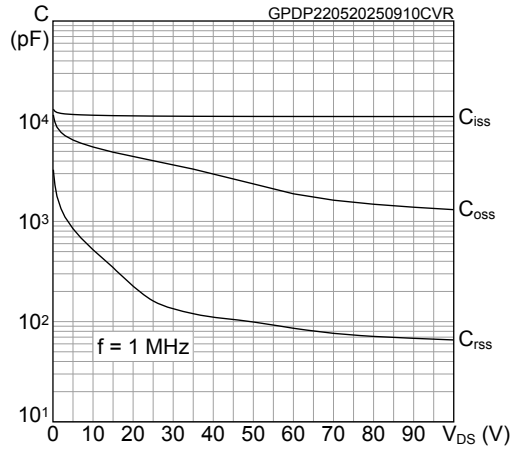


Figure 8. Avalanche characteristics

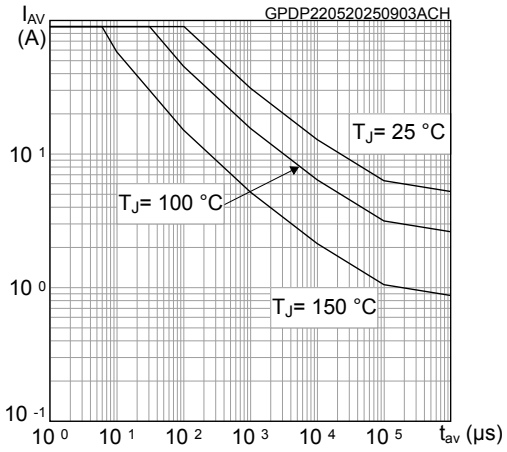


Figure 9. Typical transfer characteristics

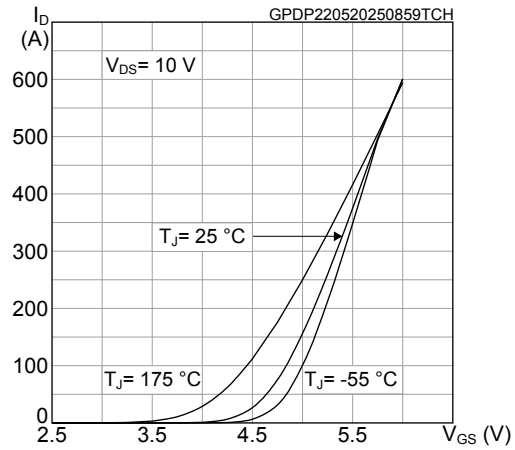


Figure 10. Avalanche energy

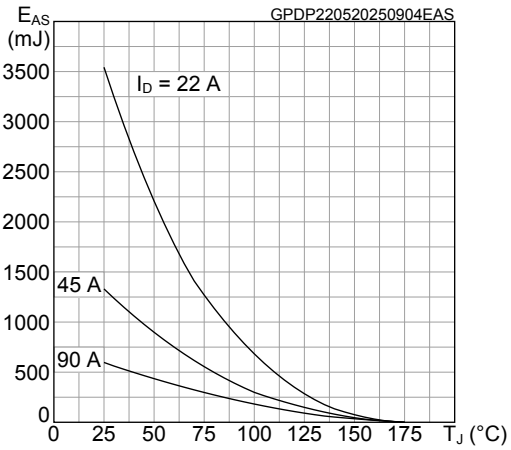


Figure 11. Typical drain-source on-resistance

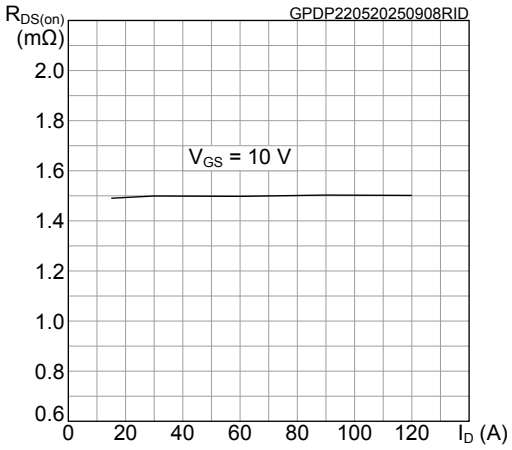


Figure 12. Typical on-resistance vs gate-source voltage

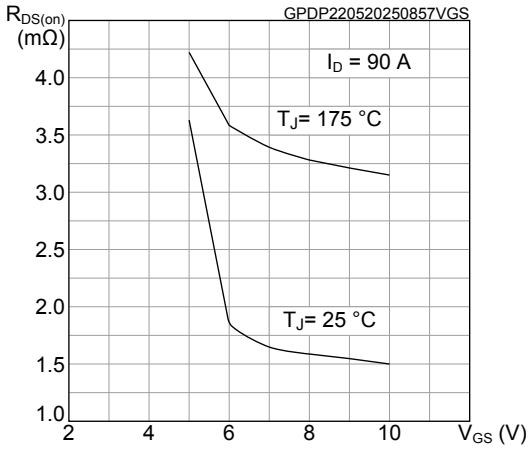


Figure 13. Normalized on-resistance vs temperature

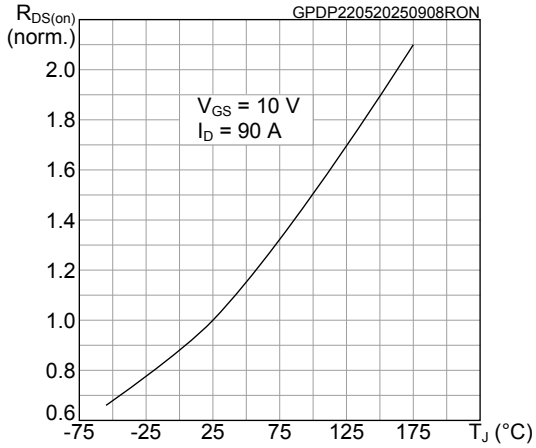


Figure 14. Normalized gate threshold voltage vs temperature

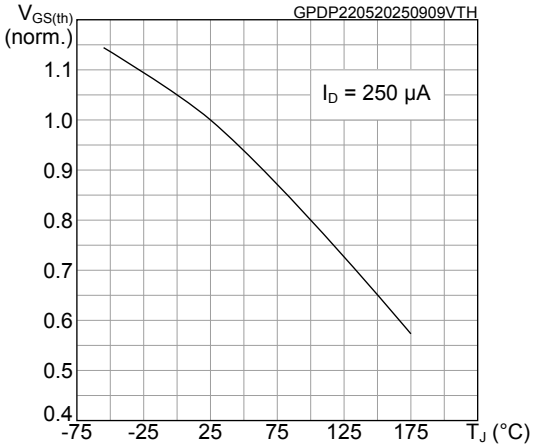


Figure 15. Typical reverse diode forward characteristics

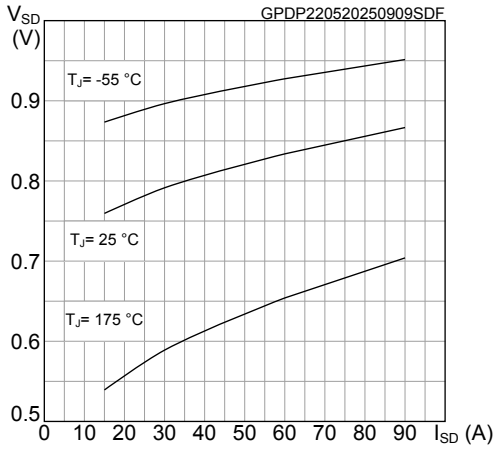
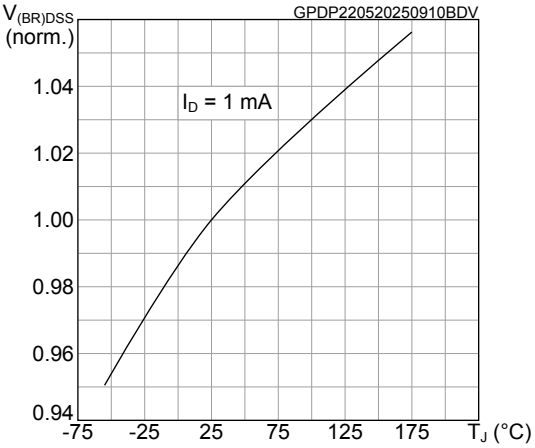


Figure 16. Normalized $V_{(BR)DSS}$ vs temperature



3 Package information

To meet environmental requirements, ST offers these devices in different grades of ECOPACK packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions, and product status are available at: www.st.com. ECOPACK is an ST trademark.

3.1 H²PAK-6 package information

Figure 17. **H²PAK-6 package outline**

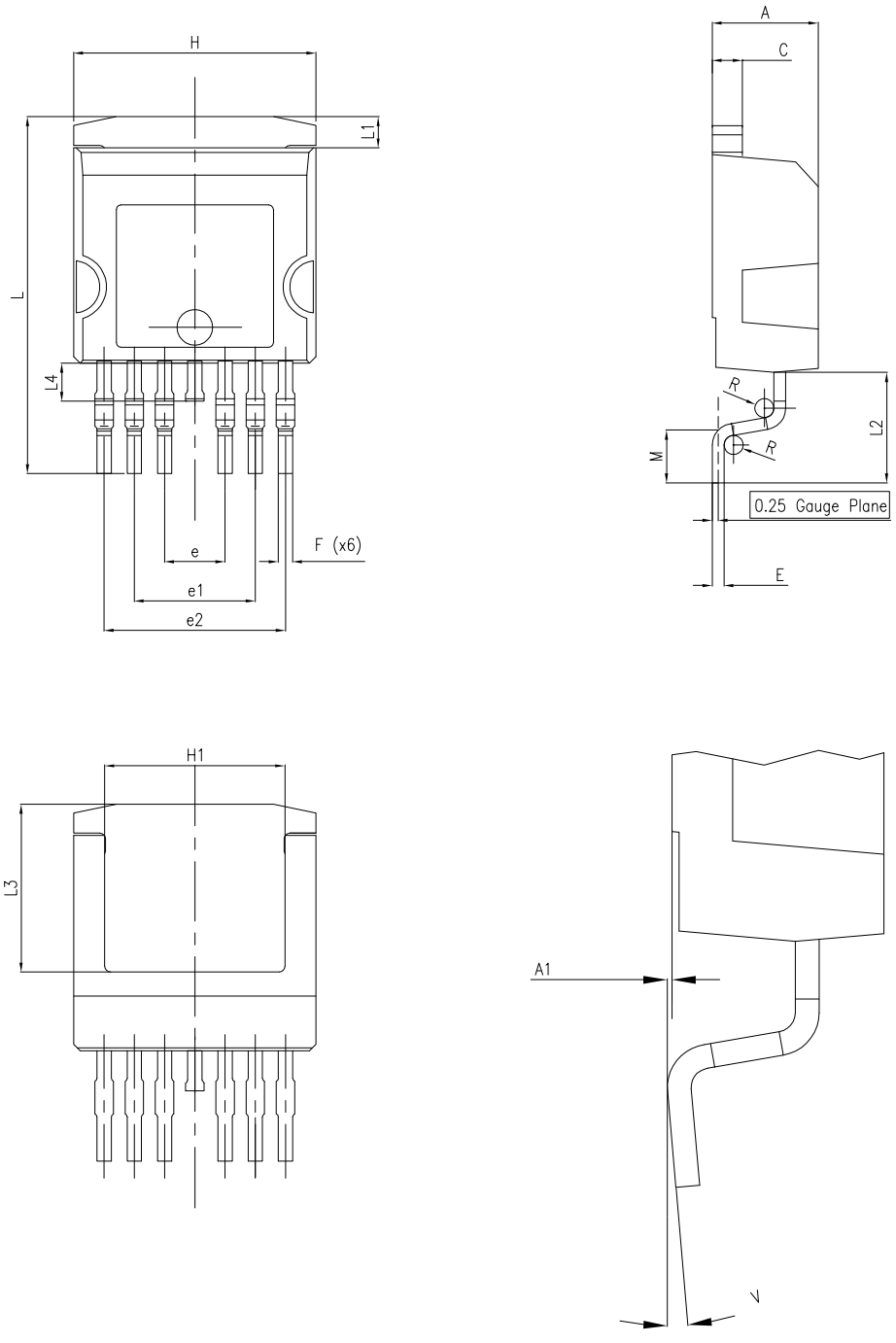
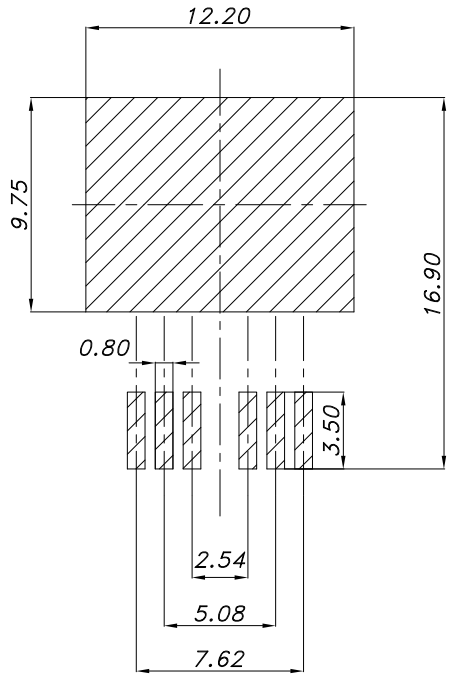


Table 7. **H²PAK-6 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.30		4.70
A1	0.03		0.20
C	1.17		1.37
e	2.34	2.54	2.74
e1	4.88		5.28
e2	7.42		7.82
E	0.45		0.60
F	0.50		0.70
H	10.00		10.40
H1	7.40		7.80
L	14.75		15.25
L1	1.27		1.40
L2	4.35		4.95
L3	6.85		7.25
L4	1.50		1.75
M	1.90		2.50
R	0.20		0.60
V	0°		8°

Figure 18. **H²PAK-6 recommended footprint**

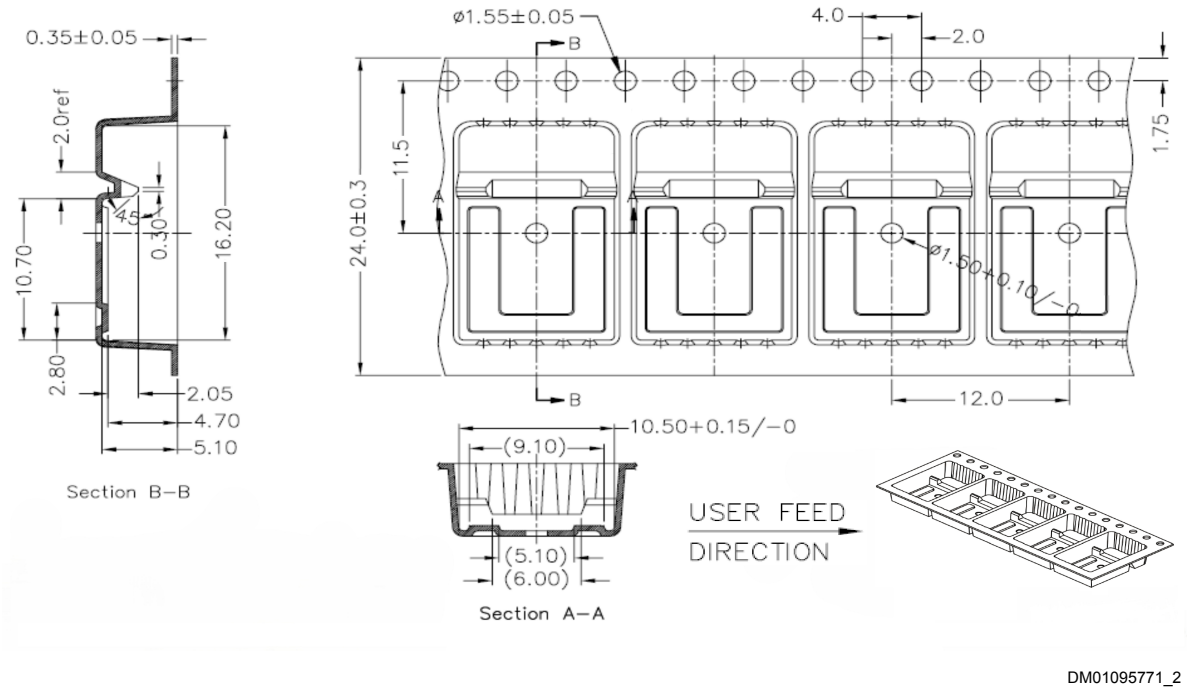


8159693_footprint_Rev_9

Note: Dimensions are in mm.

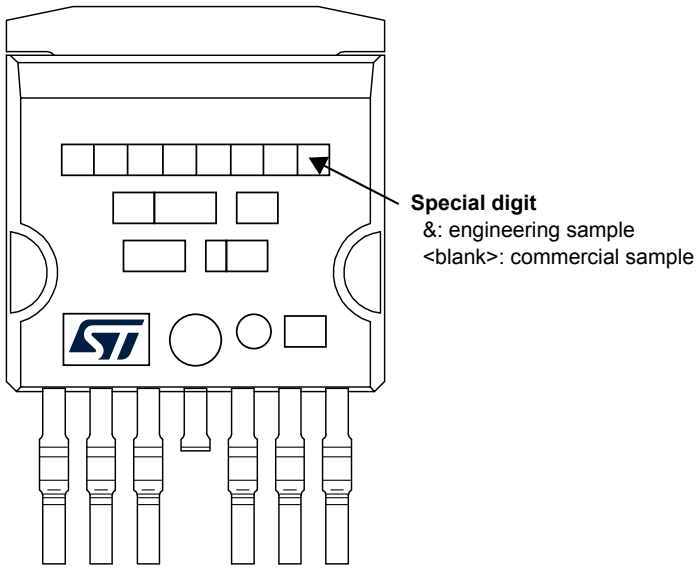
3.2 H²PAK-6 packing information

Figure 19. **H²PAK-6 tape drawing (dimensions are in mm)**



3.3 H²PAK-6 marking information

Figure 20. **H²PAK-6 marking information**



Note: Engineering Samples: these samples can be clearly identified by a dedicated special symbol in the marking of each unit. These samples are intended to be used for electrical compatibility evaluation only; usage for any other purpose may be agreed only upon written authorization by ST. ST is not liable for any customer usage in production and/or in reliability qualification trials.

Commercial Samples: fully qualified parts from ST standard production with no usage restrictions.

Revision history

Table 8. **Document revision history**

Date	Revision	Changes
21-Nov-2025	1	First release.

Contents

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